

ABSTRACT OF THE DISCLOSURE

5 A molded flexible circuit assembly and method of
forming a molded flexible circuit assembly which use a
molded stiffener, and do not require any additional type of
stiffener, are described. A molded stiffener is formed on a
flexible tape at the same time molded encapsulation units
10 are formed to encapsulate circuit die which are attached to
the flexible tape. The molded stiffeners provide adequate
rigidity for processing of the molded flexible circuit
assembly. When the stiffeners are no longer needed they are
removed at the same time the mold runners are removed. No
15 additional processing steps are required for either the
formation or removal of the molded stiffeners.

10043603-01402